

Title (en)

TESTING STATION FOR SEMICONDUCTOR WAFERS OR WAFER FRAGMENTS

Title (de)

TESTSTATION FÜR HALBLEITERWAFER BZW. BRUCHSTÜCKE VON HALBLEITERWAFERN

Title (fr)

STATION D'ESSAI POUR TRANCHES OU FRAGMENTS DE TRANCHE DE SEMI-CONDUCTEURS

Publication

**EP 0951732 A2 19991027 (DE)**

Application

**EP 98905215 A 19980107**

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Abstract (en)

[origin: DE19700839A1] The present invention pertains to a testing station for semiconductor wafers (2) or wafer fragments in a chuck-type arrangement, the substantially flat bearing surface (4) of which has a plurality of perforations (5) coupled so as to produce a removable attachment of the semiconductor wafer (2) or wafer fragment due to the suction effect exerted on said bearing surface (4) by a vacuum source. A group of perforations (5) forming a whole open out into several chambers independent of each other (15a to 17h), possibly connected to said vacuum source through a number of vacuum switches (15a to 15h). The invention also relates to a chuck-type arrangement (3) designed to measure the electronic characteristics of the semiconductor circuitry located in the group of interconnected wafers and fitted with an electronic control device to set the temperature of said bearing surface (4).

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